



Material Content Data Sheet



Sales Product Name		BSC040N10NS5		Issued		13. August 2018		
MA#		MA001708732						
Package		PG-TDSON-8-7		Weight*		119.34 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.517	1.27	1.27	12713	12713
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		317	
wire	non noble metal	copper	7440-50-8	37.762	31.63	31.67	316410	316822
	noble metal	gold	7440-57-5	0.045	0.04	0.04	374	374
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		714	
	plastics	epoxy resin	-	6.730	5.64		56390	
leadfinish	inorganic material	silicondioxide	60676-86-0	35.779	29.98	35.69	299794	356898
	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12164	12164
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1387	1387
solder	non noble metal	tin	7440-31-5	0.042	0.04		353	
	noble metal	silver	7440-22-4	0.053	0.04		441	
heatspreader	non noble metal	lead	7439-92-1	2.010	1.68	1.76	16846	17640
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
heat sink CLIP	non noble metal	iron	7439-89-6	0.011	0.01		95	
	non noble metal	copper	7440-50-8	11.320	9.49	9.50	94852	94975
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		187	
*deviation	non noble metal	copper	7440-50-8	22.292	18.68	18.71	186784	187027
						Sum in total:	100.00	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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